

L Number	Hits	Search Text	DB	Time stamp
1	0	10/064869	USPAT	2004/04/13 12:12
2	52662	DRAM and FET and (dual adj gate) and (plate adj electrode) dielectric and capacitor or storage and gate and material and oxide	USPAT	2004/04/13 12:16
3	43887	DRAM and FET and (dual adj gate) and (plate adj electrode) dielectric and capacitor or storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose	USPAT	2004/04/13 12:18
4	43867	DRAM and FET and (dual adj gate) and (plate adj electrode) dielectric and capacitor or storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose and pair and trench and doping and dope	USPAT	2004/04/13 12:23
5	43867	DRAM and FET and (dual adj gate) and (plate adj electrode) dielectric and capacitor or storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose and pair and trench and doping and dope and etch and etching and (enhanced adj soft adj error)	USPAT	2004/04/13 12:24
6	14	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor or storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose and pair and trench and doping and dope and etch and etching and (enhanced adj soft adj error)	USPAT	2004/04/13 12:26
7	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose and pair and trench and doping and dope and etch and etching and (enhanced adj soft adj error)	USPAT	2004/04/13 12:27
8	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and material and oxide and memory and stacked and SOI and buried and plurality and cell and expose and pair and trench and doping and dope and etch and etching	USPAT	2004/04/13 12:27
9	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and material and oxide and memory and SOI and buried and plurality and cell and expose and pair and doping and dope and etch and etching	USPAT	2004/04/13 12:28
10	10	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and doping	USPAT	2004/04/13 12:31
11	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and memory and SOI and plurality and cell and expose and pair and doping and dope and etching	USPAT	2004/04/13 12:29
12	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and memory and SOI and plurality and cell and expose and pair and doping and etching	USPAT	2004/04/13 12:29
13	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and memory and SOI and plurality and cell and expose and doping and etching	USPAT	2004/04/13 12:29
14	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and memory and SOI and plurality and cell and doping and etching	USPAT	2004/04/13 12:30

15	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and storage and gate and memory and plurality and cell and doping and etching	USPAT	2004/04/13 12:30
16	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and gate and memory and plurality and cell and doping and etching	USPAT	2004/04/13 12:31
17	0	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and gate and memory and plurality and cell and doping	USPAT	2004/04/13 12:31
18	10	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and doping and etching	USPAT	2004/04/13 12:31
19	10	DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and doping and etching and storage	USPAT	2004/04/13 12:32
20	10	(DRAM and FET and (dual adj gate) and (plate adj electrode) and dielectric and capacitor and doping and etching and storage) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate)	USPAT	2004/04/13 12:49
21	1	("6064588").PN.	USPAT	2004/04/13 12:49
22	1	((("6064588").PN.) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate or DRAM or dual or gate or soft or error or enhanced or dielectric or substrate or plate)	USPAT	2004/04/13 12:52
23	1	("4641165").PN.	USPAT	2004/04/13 12:52
24	1	((("4641165").PN.) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate or DRAM or dual or gate or soft or error or enhanced or dielectric or substrate or plate)	USPAT	2004/04/13 12:54
25	1	("6077745").PN.	USPAT	2004/04/13 12:53
26	1	((("6077745").PN.) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate or DRAM or dual or gate or soft or error or enhanced or dielectric or substrate or plate)	USPAT	2004/04/13 13:00
27	1	("6440801").PN.	USPAT	2004/04/13 12:56
28	1	((("6440801").PN.) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate or DRAM or dual or gate or soft or error or enhanced or dielectric or substrate or plate)	USPAT	2004/04/13 13:00
29	1	("5929477").PN.	USPAT	2004/04/13 13:00
30	1	((("5929477").PN.) and (memory or cell or portion or first or second or all or height or 0.15 or microns or plurality or expose or exposed or side or buried or oxide or insulator or capacitor or FET or rails or pair or electorde or gate or DRAM or dual or gate or soft or error or enhanced or dielectric or substrate or plate)	USPAT	2004/04/13 13:01
31	1619	438/239	USPAT	2004/04/13 13:02
32	1506	438/240	USPAT	2004/04/13 13:02
33	1104	438/241	USPAT	2004/04/13 13:02
34	321	438/242	USPAT	2004/04/13 13:02
35	920	438/243	USPAT	2004/04/13 13:02
36	597	438/244	USPAT	2004/04/13 13:02
37	277	438/246	USPAT	2004/04/13 13:02

38	298	438/248	USPAT	2004/04/13 13:02
39	570	438/250	USPAT	2004/04/13 13:03
40	3217	438/253	USPAT	2004/04/13 13:03
41	724	438/266	USPAT	2004/04/13 13:03
42	918	438/270	USPAT	2004/04/13 13:03
43	337	438/278	USPAT	2004/04/13 13:03
44	350	438/283	USPAT	2004/04/13 13:03
45	2363	438/305	USPAT	2004/04/13 13:03
46	876	438/306	USPAT	2004/04/13 13:03
47	324	438/311	USPAT	2004/04/13 13:04
48	1047	438/381	USPAT	2004/04/13 13:04
49	884	438/386	USPAT	2004/04/13 13:04
50	461	438/387	USPAT	2004/04/13 13:04
51	624	438/393	USPAT	2004/04/13 13:04
52	157	438/394	USPAT	2004/04/13 13:04
53	3147	438/396	USPAT	2004/04/13 13:04

4/13/04